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Part Number: [0736590002](#)
Status: **Active**
Overview: [HDM Backplane Connector System](#)
Description: HDM Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 12 Circuits, Gold (Au) 0.76µm, Pin Length 2.50mm

Documents:

[3D Model](#) [Packaging Specification PK-70873-0819 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

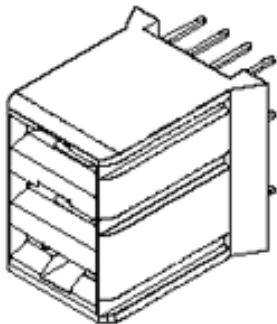
CSA LR19980
UL E29179

General

Product Family Backplane Connectors
Series [73659](#)
Application Backplane
Comments Midplane Power Module
Component Type Power Header
Overview [HDM Backplane Connector System](#)
Product Name HDM
UPC 800755024838

Physical

Circuits (Loaded) 12
Circuits (maximum) 12
Color - Resin Black
Durability (mating cycles max) 250
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part No
Keying to Mating Part None
Material - Metal Beryllium Copper
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
Net Weight 1.609/g
Number of Columns 1
Number of Pairs Open Pin Field
Number of Rows 3
Orientation Vertical
PC Tail Length 2.50mm
PCB Locator No
PCB Retention Yes
PCB Thickness - Recommended 2.50mm
Packaging Type Tube
Pitch - Mating Interface 2.00mm
Pitch - Termination Interface 2.00mm
Plating min - Mating 0.762µm
Plating min - Termination 3.810µm
Polarized to PCB No
Stackable Yes
Surface Mount Compatible (SMC) Yes
Temperature Range - Operating -55° to +105°C
Termination Interface: Style Through Hole



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Compliant

REACH SVHC

Not Contained Per -
ED/61/2018 (27 June
2018)

Halogen-Free

Status

Low-Halogen

For more information, please visit [Contact US](#)

China ROHS

Green Image

ELV

Not Relevant

RoHS Phthalates

Not Contained

Search Parts in this Series

[73659](#) Series

Mates With

[73651](#) HDM Board-to-Board Daughterboard
Power Module

Electrical

Current - Maximum per Contact	15.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	38
Shielded	Yes
Voltage - Maximum	500V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	040
Lead-freeProcess Capability	REFLOW
Max. Cycles at Max. Process Temperature	003
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0819
Sales Drawing	SDA-73659-000*

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